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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	9.2 ns
Voltage Supply - Internal	1.7V ~ 1.9V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	12000
Number of I/O	173
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2c512-10pqg208c

By mapping a signal to the DataGATE function, lower power can be achieved due to reduction in signal switching.

Another feature that eases voltage translation is I/O banking. Four I/O banks are available on the CoolRunner-II 512 macrocell device that permits easy interfacing to 3.3V, 2.5V, 1.8V, and 1.5V devices.

The CoolRunner-II 512 macrocell CPLD is I/O compatible with various JEDEC I/O standards (see [Table 1](#)). This device is also 1.5V I/O compatible with the use of Schmitt-trigger inputs.

RealDigital Design Technology

Xilinx CoolRunner-II CPLDs are fabricated on a 0.18 micron process technology which is derived from leading edge FPGA product development. CoolRunner-II CPLDs employ RealDigital, a design technique that makes use of CMOS technology in both the fabrication and design methodology. RealDigital design technology employs a cascade of CMOS gates to implement sum of products instead of traditional sense amplifier methodology. Due to this technology, Xilinx CoolRunner-II CPLDs achieve both high-performance and low power operation.

Supported I/O Standards

The CoolRunner-II 512 macrocell features LVCMOS, LVTTTL, SSTL, and HSTL I/O implementations. See [Table 1](#)

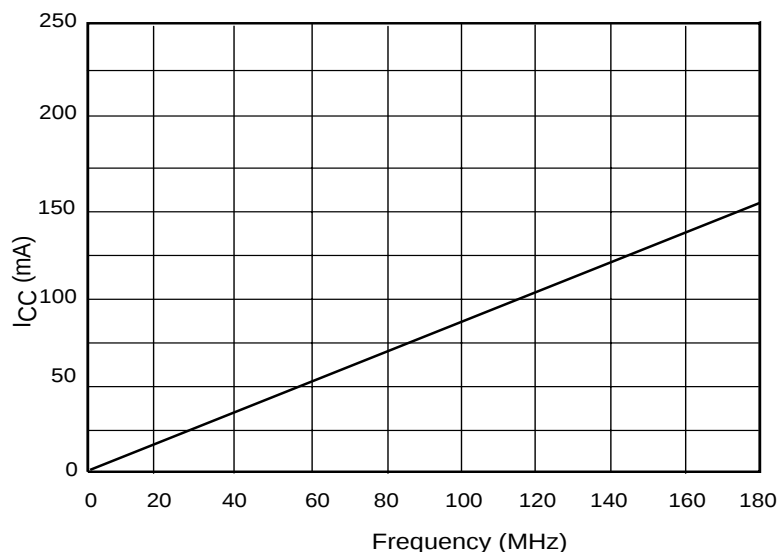
for I/O standard voltages. The LVTTTL I/O standard is a general purpose EIA/JEDEC standard for 3.3V applications that use an LVTTTL input buffer and Push-Pull output buffer. The LVCMOS standard is used in 3.3V, 2.5V, 1.8V applications. Both HSTL and SSTL I/O standards make use of a V_{REF} pin for JEDEC compliance. CoolRunner-II CPLDs are also 1.5V I/O compatible with the use of Schmitt-trigger inputs.

Table 1: I/O Standards for XC2C512⁽¹⁾

IOSTANDARD Attribute	Output V_{CCIO}	Input V_{CCIO}	Input V_{REF}	Board Termination Voltage V_{TT}
LVTTTL	3.3	3.3	N/A	N/A
LVCMOS33	3.3	3.3	N/A	N/A
LVCMOS25	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
LVCMOS15 ⁽²⁾	1.5	1.5	N/A	N/A
HSTL_1	1.5	1.5	0.75	0.75
SSTL2_1	2.5	2.5	1.25	1.25
SSTL3_1	3.3	3.3	1.5	1.5

(1) For information on Vref pins, see [XAPP399](#).

(2) LVCMOS15 requires Schmitt-trigger inputs.



DS096_01_030705

Figure 1: I_{CC} vs Frequency

Table 2: I_{CC} vs Frequency (LVCMOS 1.8V $T_A = 25^\circ\text{C}$)⁽¹⁾

	Frequency (MHz)									
	0	20	40	60	80	100	120	140	160	180
Typical I_{CC} (mA)	0.025	17.22	34.37	52.04	69.44	86.85	105.13	122.68	140.23	157.78

Notes:

- 16-bit up/down, Resettable binary counter (one counter per function block).

Absolute Maximum Ratings

Symbol	Description	Value	Units
V_{CC}	Supply voltage relative to ground	–0.5 to 2.0	V
V_{CCIO}	Supply voltage for output drivers	–0.5 to 4.0	V
$V_{JTAG}^{(2)}$	JTAG input voltage limits	–0.5 to 4.0	V
V_{CCAUX}	JTAG input supply voltage	–0.5 to 4.0	V
$V_{IN}^{(1)}$	Input voltage relative to ground ⁽¹⁾	–0.5 to 4.0	V
$V_{TS}^{(1)}$	Voltage applied to 3-state output ⁽¹⁾	–0.5 to 4.0	V
$T_{STG}^{(3)}$	Storage Temperature (ambient)	–65 to +150	°C
T_J	Junction Temperature	+150	°C

Notes:

- Maximum DC undershoot below GND must be limited to either 0.5V or 10 mA, whichever is easiest to achieve. During transitions, the device pins may undershoot to –2.0v or overshoot to +4.5V, provided this over or undershoot lasts less than 10 ns and with the forcing current being limited to 200 mA.
- Valid over commercial temperature range.
- For soldering guidelines and thermal considerations, see the [Device Packaging](#) information on the Xilinx website. For Pb free packages, see [XAPP427](#).

Recommended Operating Conditions

Symbol	Parameter		Min	Max	Units
V _{CC}	Supply voltage for internal logic and input buffers	Commercial T _A = 0°C to +70°C	1.7	1.9	V
		Industrial T _A = −40°C to +85°C	1.7	1.9	V
V _{CCIO}	Supply voltage for output drivers @ 3.3V operation		3.0	3.6	V
	Supply voltage for output drivers @ 2.5V operation		2.3	2.7	V
	Supply voltage for output drivers @ 1.8V operation		1.7	1.9	V
	Supply voltage for output drivers @ 1.5V operation		1.4	1.6	V
V _{CCAUX}	JTAG programming		1.7	3.6	V

DC Electrical Characteristics (Over Recommended Operating Conditions)

Symbol	Parameter	Test Conditions	Typical	Max.	Units
I_{CCSB}	Standby current Commercial	$V_{CC} = 1.9\text{V}$, $V_{CCIO} = 3.6\text{V}$	50	240	μA
I_{CCSB}	Standby current Industrial	$V_{CC} = 1.9\text{V}$, $V_{CCIO} = 3.6\text{V}$	150	400	μA
$I_{CC}^{(1)}$	Dynamic current	$f = 1\text{ MHz}$	-	1	mA
		$f = 50\text{ MHz}$	-	55	mA
C_{JTAG}	JTAG input capacitance	$f = 1\text{ MHz}$	-	10	pF
C_{CLK}	Global clock input capacitance	$f = 1\text{ MHz}$	-	12	pF
C_{IO}	I/O capacitance	$f = 1\text{ MHz}$	-	10	pF
$I_{IL}^{(2)}$	Input leakage current	$V_{IN} = 0\text{V}$ or V_{CCIO} to 3.9V	-	+/-1	μA
$I_{IH}^{(2)}$	I/O High-Z leakage	$V_{IN} = 0\text{V}$ or V_{CCIO} to 3.9V	-	+/-1	μA

Notes:

- 16-bit up/down, Resettable binary counter (one counter per function block) tested at $V_{CC} = V_{CCIO} = 1.9\text{V}$.
- See Quality and Reliability section of the CoolRunner-II family data sheet.

LVC MOS 3.3V and LV TTL 3.3V DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	3.0	3.6	V
V_{IH}	High level input voltage	-	2	3.9	V
V_{IL}	Low level input voltage	-	-0.3	0.8	V
V_{OH}	High level output voltage	$I_{OH} = -8\text{ mA}$, $V_{CCIO} = 3\text{V}$	$V_{CCIO} - 0.4\text{V}$	-	V
		$I_{OH} = -0.1\text{ mA}$, $V_{CCIO} = 3\text{V}$	$V_{CCIO} - 0.2\text{V}$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8\text{ mA}$, $V_{CCIO} = 3\text{V}$	-	0.4	V
		$I_{OL} = 0.1\text{ mA}$, $V_{CCIO} = 3\text{V}$	-	0.2	V

LVC MOS 2.5V DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	2.3	2.7	V
V_{IH}	High level input voltage	-	1.7	$V_{CCIO} + 0.3^{(1)}$	V
V_{IL}	Low level input voltage	-	-0.3	0.7	V
V_{OH}	High level output voltage	$I_{OH} = -8\text{ mA}$, $V_{CCIO} = 2.3\text{V}$	$V_{CCIO} - 0.4\text{V}$	-	V
		$I_{OH} = -0.1\text{ mA}$, $V_{CCIO} = 2.3\text{V}$	$V_{CCIO} - 0.2\text{V}$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8\text{ mA}$, $V_{CCIO} = 2.3\text{V}$	-	0.4	V
		$I_{OL} = 0.1\text{ mA}$, $V_{CCIO} = 2.3\text{V}$	-	0.2	V

(1) The V_{IH} Max value represents the JEDEC specification for LVC MOS25. The CoolRunner-II input buffer can tolerate up to 3.9V without physical damage.

LVC MOS 1.8V DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	1.7	1.9	V
V_{IH}	High level input voltage	-	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3^{(1)}$	V
V_{IL}	Low level input voltage	-	-0.3	$0.35 \times V_{CCIO}$	V
V_{OH}	High level output voltage	$I_{OH} = -8\text{ mA}$, $V_{CCIO} = 1.7\text{V}$	$V_{CCIO} - 0.45$	-	V
		$I_{OH} = -0.1\text{ mA}$, $V_{CCIO} = 1.7\text{V}$	$V_{CCIO} - 0.2$	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8\text{ mA}$, $V_{CCIO} = 1.7\text{V}$	-	0.45	V
		$I_{OL} = 0.1\text{ mA}$, $V_{CCIO} = 1.7\text{V}$	-	0.2	V

(1) The V_{IH} Max value represents the JEDEC specification for LVC MOS18. The CoolRunner-II input buffer can tolerate up to 3.9V without physical damage.

LVC MOS 1.5V DC Voltage Specifications⁽¹⁾

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{CCIO}	Input source voltage	-	1.4	1.6	V
V_{IH}	High level input voltage	-	$0.5 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	V
V_{IL}	Low level input voltage	-	$0.2 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	V

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _{OH}	High level output voltage	I _{OH} = -8 mA, V _{CCIO} = 1.4V	V _{CCIO} - 0.45	-	V
		I _{OH} = -0.1 mA, V _{CCIO} = 1.4V	V _{CCIO} - 0.2	-	V
V _{OL}	Low level output voltage	I _{OL} = 8 mA, V _{CCIO} = 1.4V	-	0.4	V
		I _{OL} = 0.1 mA, V _{CCIO} = 1.4V	-	0.2	V

Notes:

1. Hysteresis used on 1.5V inputs.

Schmitt Trigger Input DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _{CCIO}	Input source voltage		1.4	3.9	V
V _{T+}	Input hysteresis threshold voltage		0.5 x V _{CCIO}	0.8 x V _{CCIO}	V
V _{T-}			0.2 x V _{CCIO}	0.5 x V _{CCIO}	V

SSTL2-1 DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Units
V _{CCIO}	Input source voltage		2.3	2.5	2.7	V
V _{REF} ⁽¹⁾	Input reference voltage		1.15	1.25	1.35	V
V _{TT} ⁽²⁾	Termination voltage		V _{REF} - 0.04	1.25	V _{REF} + 0.04	V
V _{IH}	High level input voltage		V _{REF} + 0.18	-	3.9	V
V _{IL}	Low level input voltage		-0.3	-	V _{REF} - 0.18	V
V _{OH}	High level output voltage	I _{OH} = -8 mA, V _{CCIO} = 2.3V	V _{CCIO} - 0.62	-	-	V
V _{OL}	Low level output voltage	I _{OL} = 8 mA, V _{CCIO} = 2.3V	-	-	0.54	V

Notes:

1. V_{REF} should track the variations in V_{CCIO}, also peak to peak AC noise on V_{REF} may not exceed ±2% V_{REF}
2. V_{TT} of transmitting device must track V_{REF} of receiving devices

SSTL3-1 DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Units
V _{CCIO}	Input source voltage		3.0	3.3	3.6	V
V _{REF} ⁽¹⁾	Input reference voltage		1.3	1.5	1.7	V
V _{TT} ⁽²⁾	Termination voltage		V _{REF} - 0.05	1.5	V _{REF} + 0.05	V
V _{IH}	High level input voltage		V _{REF} + 0.2	-	V _{CCIO} + 0.3	V
V _{IL}	Low level input voltage		-0.3	-	V _{REF} - 0.2	V
V _{OH}	High level output voltage	I _{OH} = -8 mA, V _{CCIO} = 3V	V _{CCIO} - 1.1	-	-	V
V _{OL}	Low level output voltage	I _{OL} = 8 mA, V _{CCIO} = 3V	-	-	0.7	V

Notes:

1. V_{REF} should track the variations in V_{CCIO}, also peak to peak AC noise on V_{REF} may not exceed ±2% V_{REF}
2. V_{TT} of transmitting device must track V_{REF} of receiving devices

HSTL1 DC Voltage Specifications

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Units
V_{CCIO}	Input source voltage		1.4	1.5	1.6	V
$V_{REF}^{(1)}$	Input reference voltage		0.68	0.75	0.90	V
$V_{TT}^{(2)}$	Termination voltage		-	$V_{CCIO} \times 0.5$	-	V
V_{IH}	High level input voltage		$V_{REF} + 0.1$	-	1.9	V
V_{IL}	Low level input voltage		-0.3	-	$V_{REF} - 0.1$	V
V_{OH}	High level output voltage	$I_{OH} = -8 \text{ mA}$, $V_{CCIO} = 1.7\text{V}$	$V_{CCIO} - 0.4$	-	-	V
V_{OL}	Low level output voltage	$I_{OL} = 8 \text{ mA}$, $V_{CCIO} = 1.7\text{V}$	-	-	0.4	V

Notes:

- V_{REF} should track the variations in V_{CCIO} , also peak-to-peak AC noise on V_{REF} may not exceed $\pm 2\% V_{REF}$
- V_{TT} of transmitting device must track V_{REF} of receiving devices

AC Electrical Characteristics Over Recommended Operating Conditions

Symbol	Parameter	-7		-10		Units
		Min.	Max.	Min.	Max.	
T _{PD1}	Propagation delay (single p-term)	-	7.1	-	9.2	ns
T _{PD2}	Propagation delay (OR array)	-	7.5	-	10.0	ns
T _{SUD}	Direct input register set-up time	3.4	-	4.0	-	ns
T _{SU1}	Setup time fast (single p-term)	2.6	-	3.1	-	ns
T _{SU2}	Setup time (OR array)	3.0	-	3.9	-	ns
T _H	Direct input register hold time	0	-	0	-	ns
T _H	P-term hold time	0	-	0	-	ns
T _{CO}	Clock to output	-	5.8	-	7.9	ns
F _{TOGGLE} ⁽¹⁾	Internal toggle rate	-	250	-	166	MHz
F _{SYSTEM1} ⁽²⁾	Maximum system frequency	-	179	-	128	MHz
F _{SYSTEM2} ⁽²⁾	Maximum system frequency	-	167	-	116	MHz
F _{EXT1} ⁽³⁾	Maximum external frequency	-	119	-	91	MHz
F _{EXT2} ⁽³⁾	Maximum external frequency	-	114	-	85	MHz
T _{PSUD}	Direct input register p-term clock setup time	2.1	-	2.8	-	ns
T _{PSU1}	P-term clock setup time (single p-term)	1.1	-	1.7	-	ns
T _{PSU2}	P-term clock setup time (OR array)	1.5	-	2.5	-	ns
T _{PHD}	Direct input register p-term clock hold time	0.1	-	0.4	-	ns
T _{PH}	P-term clock hold	1.3	-	1.7	-	ns
T _{PCO}	P-term clock to output	-	7.3	-	9.3	ns
T _{OE} /T _{OD}	Global OE to output enable/disable	-	6.5	-	9.2	ns
T _{POE} /T _{POD}	P-term OE to output enable/disable	-	7.5	-	10.2	ns
T _{MOE} /T _{MOD}	Macrocell driven OE to output enable/disable	-	8.6	-	12.5	ns
T _{PAO}	P-term set/reset to output valid	-	7.6	-	11.6	ns
T _{AO}	Global set/reset to output valid	-	7.5	-	11.5	ns
T _{SUEC}	Register clock enable setup time	2.8	-	3.2	-	ns
T _{HEC}	Register clock enable hold time	0	-	0	-	ns
T _{CW}	Global clock pulse width High or Low	2.0	-	3.0	-	ns
T _{PCW}	P-term pulse width High or Low	7.5	-	10.0	-	ns
T _{APRPW}	Asynchronous preset/reset pulse width (High or Low)	7.5	-	10.0	-	ns
T _{DGSU}	Set-up before DataGATE latch assertion	0.0	-	0.0	-	ns
T _{DGH}	Hold to DataGATE latch assertion	4.0	-	6.0	-	ns
T _{DGR}	DataGATE recovery to new data	-	9.3	-	11.0	ns
T _{DGW}	DataGATE low pulse width	3.0	-	5.0	-	ns
T _{CDRSU}	CDRST setup time before falling edge GCLK2	1.7	-	2.5	-	ns
T _{CDRH}	Hold time CDRST after falling edge GCLK2	0	-	0	-	ns
T _{CONFIG} ⁽⁴⁾	Configuration time	-	400	-	400	μs

Notes:

1. F_{TOGGLE} is the maximum clock frequency to which a T-Flip Flop can reliably toggle (see the CoolRunner-II family data sheet for more information).
2. F_{SYSTEM1} (1/T_{CYCLE}) is the internal operating frequency for a device fully populated with 16-bit Resettable binary counter through one p-term per macrocell while F_{SYSTEM2} is through the OR array.
3. F_{EXT1}(1/T_{SU1}+T_{CO}) is the maximum external frequency using one p-term while F_{EXT2} is through the OR array
4. Typical configuration current during T_{CONFIG} is approximately 15mA

Internal Timing Parameters⁽¹⁾

Symbol	Parameter ⁽¹⁾	-7		-10		Units
		Min.	Max.	Min.	Max.	
Buffer Delays						
T _{IN}	Input buffer delay	-	3.1	-	3.8	ns
T _{DIN}	Direct data register input delay	-	4.4	-	5.5	ns
T _{GCK}	Global Clock buffer delay	-	2.4	-	3.3	ns
T _{GSR}	Global set/reset buffer delay	-	3.8	-	4.6	ns
T _{GTS}	Global 3-state buffer delay	-	2.9	-	3.7	ns
T _{OUT}	Output buffer delay	-	3.0	-	3.9	ns
T _{EN}	Output buffer enable/disable delay	-	3.6	-	5.5	ns
P-term Delays						
T _{CT}	Control term delay	-	0.8	-	0.9	ns
T _{LOGI1}	Single P-term delay adder	-	0.5	-	0.8	ns
T _{LOGI2}	Multiple P-term delay adder	-	0.4	-	0.8	ns
Macrocell Delay						
T _{PDI}	Input to output valid	-	0.5	-	0.7	ns
T _{SUI}	Setup before clock	1.4	-	1.8	-	ns
T _{HI}	Hold after clock	0	-	0	-	ns
T _{ECSU}	Enable clock setup time	1.3	-	1.8	-	ns
T _{ECHO}	Enable clock hold time	0	-	0	-	ns
T _{COI}	Clock to output valid	-	0.4	-	0.7	ns
T _{AOI}	Set/reset to output valid	-	0.7	-	3.0	ns
T _{CDBL}	Clock doubler delay	-	0	-	0	ns
Feedback Delays						
T _F	Feedback delay	-	3.3	-	4.5	ns
T _{OEM}	Macrocell to global OE delay	-	2.2	-	3.0	ns
I/O Standard Time Adder Delays 1.5V CMOS						
T _{HYS15}	Hysteresis input adder	-	3.0	-	4.0	ns
T _{OUT15}	Output adder	-	0.8	-	1.0	ns
T _{SLEW15}	Output slew rate adder	-	3.0	-	4.0	ns
I/O Standard Time Adder Delays 1.8V CMOS						
T _{HYS18}	Hysteresis input adder	-	2.0	-	3.0	ns
T _{OUT18}	Output adder	-	0	-	0	ns
T _{SLEW18}	Output slew rate adder	-	2.5	-	4.0	ns

Internal Timing Parameters⁽¹⁾ (Continued)

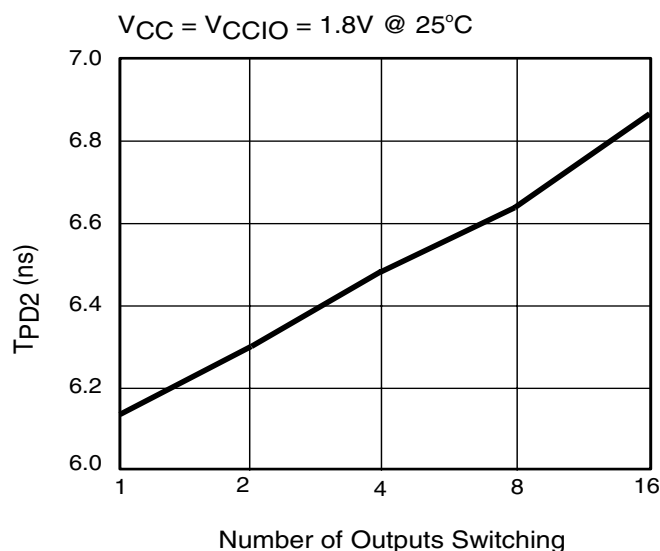
Symbol	Parameter ⁽¹⁾	-7		-10		Units
		Min.	Max.	Min.	Max.	
I/O Standard Time Adder Delays 2.5V CMOS						
T _{IN25}	Standard input adder	-	0.6	-	1.0	ns
T _{HYS25}	Hysteresis input adder	-	1.5	-	3.0	ns
T _{OUT25}	Output adder	-	0.8	-	2.0	ns
T _{SLEW25}	Output slew rate adder	-	3.0	-	4.0	ns
I/O Standard Time Adder Delays 3.3V CMOS/TTL						
T _{IN33}	Standard input adder	-	0.5	-	2.0	ns
T _{HYS33}	Hysteresis input adder	-	1.2	-	3.0	ns
T _{OUT33}	Output adder	-	1.2	-	3.0	ns
T _{SLEW33}	Output slew rate adder	-	3.0	-	4.0	ns
I/O Standard Time Adder Delays HSTL, SSTL						
SSTL2-1	Input adder to T _{IN} , T _{DIN} , T _{GCK} , T _{GSR} ,T _{GTS}	-	0.4	-	1.0	ns
	Output adder to T _{OUT}	-	-0.5	-	0.0	ns
SSTL3-1	Input adder to T _{IN} , T _{DIN} , T _{GCK} , T _{GSR} ,T _{GTS}	-	0.6	-	1.0	ns
	Output adder to T _{OUT}	-	0.0	-	0.0	ns
HSTL-1	Input adder to T _{IN} , T _{DIN} , T _{GCK} , T _{GSR} ,T _{GTS}	-	0.8	-	1.0	ns
	Output adder to T _{OUT}	-	0.0	-	0.0	ns

Notes:

1. 1.5 ns input pin signal rise/fall.

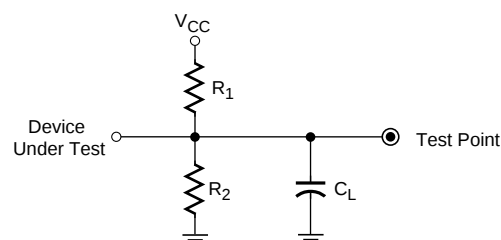
Switching Characteristics

AC Test Circuit



DS096_02_022003

Figure 2: Derating Curve for T_{PD}



Output Type	R_1	R_2	C_L
LVTTL33	268 Ω	235 Ω	35 pF
LVC MOS33	275 Ω	275 Ω	35 pF
LVC MOS25	188 Ω	188 Ω	35 pF
LVC MOS18	112.5 Ω	112.5 Ω	35 pF
LVC MOS15	150 Ω	150 Ω	35 pF

C_L includes test fixtures and probe capacitance.

1.5 nsec maximum rise/fall times on inputs.

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Figure 3: Load Circuit

Typical I/O Output Curves

The I/V curve illustrates the nominal amount of current that an I/O can source/sink at different voltage levels.

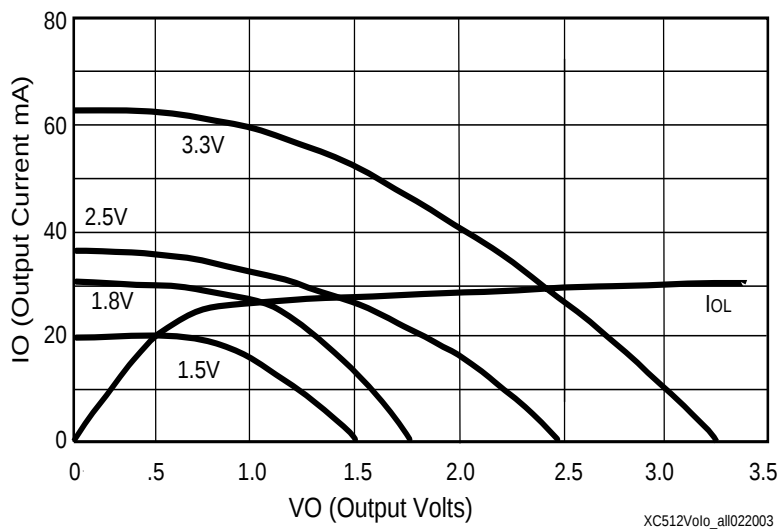


Figure 4: Typical I/V Curves for XC2C512

Pin Descriptions

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
1(GTS0)	1	7	D4	C1	2
1	2	6	B2	C2	2
1(GTS3)	3	5	E3	B1	2
1	4	4	C3	B2	2
1	5	-	-	-	-
1	6	-	-	-	-
1	7	-	-	-	-
1	8	-	-	-	-
1	9	-	-	-	-
1	10	-	-	-	-
1	11	-	-	-	-
1	12	-	-	-	-
1(GTS2)	13	3	D3	D3	2
1	14	2	B3	C3	2
1	15	208	B4	A1	2
1(GSR)	16	206	C4	A2	2
2	1	-	A1	D2	2
2	2	8	-	D1	2
2	3	-	D2	F4	2
2	4	-	-	F3	2
2	5	-	-	-	-
2	6	-	-	-	-
2	7	-	-	-	-
2	8	-	-	-	-
2	9	-	-	-	-
2	10	-	-	-	-
2	11	-	-	-	-
2	12	-	-	-	-
2	13	-	C2	E2	2
2(GTS1)	14	9	E5	E1	2
2	15	10	B1	F2	2
2	16	12	E4	G4	2

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
3	1	205	-	B3	2
3	2	-	A2	C4	2
3	3	203	-	B4	2
3	4	-	C5	C5	2
3	5	202	A3	B5	2
3	6	-	-	-	-
3	7	-	-	-	-
3	8	-	-	-	-
3	9	-	-	-	-
3	10	-	-	-	-
3	11	-	-	-	-
3	12	-	-	-	-
3	13	201	E7	A3	2
3	14	-	A4	A4	2
3	15	200	C6	D6	2
3	16	199	B5	A5	2
4	1	-	C1	G3	2
4	2	14	E2	G2	2
4	3	-	F2	G1	2
4	4	15	E6	H4	2
4	5	-	-	-	-
4	6	-	-	-	-
4	7	-	-	-	-
4	8	-	-	-	-
4	9	-	-	-	-
4	10	-	-	-	-
4	11	-	-	-	-
4	12	-	-	-	-
4	13	-	F3	H3	2
4	14	16	D1	H2	2
4	15	17	G4	H1	2
4	16	18	E1	J4	2

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
5	1	198	D6	C6	2
5	2	197	A5	B6	2
5	3	196	E8	A6	2
5	4	195	B6	D7	2
5	5	194	C7	C7	2
5	6	-	-	-	-
5	7	-	-	-	-
5	8	-	-	-	-
5	9	-	-	-	-
5	10	-	-	-	-
5	11	-	-	-	-
5	12	-	-	-	-
5	13	193	-	B7	2
5	14	-	A6	A7	2
5	15	192	D7	D8	2
5	16	-	B7	C8	2
6	1	19	G3	J3	2
6	2	20	G2	J2	2
6	3	21	-	J1	2
6	4	-	F5	K4	2
6	5	-	-	-	-
6	6	-	-	-	-
6	7	-	-	-	-
6	8	-	-	-	-
6	9	-	-	-	-
6	10	-	-	-	-
6	11	-	-	-	-
6	12	-	-	-	-
6	13	-	-	K3	2
6	14	-	F1	K2	2
6	15	-	-	K1	2
6	16	-	G5	L1	2

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
7	1	191	-	B8	2
7	2	-	E9	A8	2
7	3	189	A7	D9	2
7	4	188	D8	C9	2
7	5	187	B8	B9	2
7	6	-	-	-	-
7	7	-	-	-	-
7	8	-	-	-	-
7	9	-	-	-	-
7	10	-	-	-	-
7	11	-	-	-	-
7	12	-	-	-	-
7	13	186	C8	A9	2
7	14	185	A8	D10	2
7	15	184	E11	C10	2
7	16	183	E10	B10	2
8	1	-	H2	L4	2
8	2	22	-	L3	2
8	3	23	H4	L2	2
8	4	-	-	M1	2
8	5	-	-	-	-
8	6	-	-	-	-
8	7	-	-	-	-
8	8	-	-	-	-
8	9	-	-	-	-
8	10	-	-	-	-
8	11	-	-	-	-
8	12	-	-	-	-
8	13	-	G1	M2	2
8	14	25	H3	M3	2
8	15	-	H1	M4	2
8	16	-	H5	N1	2

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
13	1	37	-	U1	1
13	2	-	K4	T4	1
13	3	36	L2	T3	1
13	4	35	-	T2	1
13	5	-	-	-	-
13	6	-	-	-	-
13	7	-	-	-	-
13	8	-	-	-	-
13	9	-	-	-	-
13	10	-	-	-	-
13	11	-	-	-	-
13	12	-	-	-	-
13	13	-	K3	T1	1
13	14	34	L1	R4	1
13	15	32	K5	R3	1
13	16	-	K2	R2	1
14	1	-	M6	Y8	1
14	2	-	-	AA8	1
14	3	69	T3	AB8	1
14	4	70	P6	W9	1
14	5	71	T4	Y9	1
14	6	-	-	-	-
14	7	-	-	-	-
14	8	-	-	-	-
14	9	-	-	-	-
14	10	-	-	-	-
14	11	-	-	-	-
14	12	-	-	-	-
14	13	72	P7	AA9	1
14	14	-	-	AB9	1
14	15	73	T5	W10	1
14	16	-	-	Y10	1

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
15	1	31	J4	R1	1
15	2	-	K1	P4	1
15	3	30	J3	P3	1
15	4	29	J2	P2	1
15	5	-	-	-	-
15	6	-	-	-	-
15	7	-	-	-	-
15	8	-	-	-	-
15	9	-	-	-	-
15	10	-	-	-	-
15	11	-	-	-	-
15	12	-	-	-	-
15	13	28	J5	P1	1
15	14	27	J1	N4	1
15	15	-	-	N3	1
15	16	-	-	N2	1
16	1	74	N7	AA10	1
16	2	-	-	AB10	1
16	3	75	R7	AB11	1
16	4	76	M7	W11	1
16	5	77	T6	AA11	1
16	6	-	-	-	-
16	7	-	-	-	-
16	8	-	-	-	-
16	9	-	-	-	-
16	10	-	-	-	-
16	11	-	-	-	-
16	12	-	-	-	-
16	13	-	-	Y11	1
16	14	78	-	AB12	1
16	15	-	-	AA12	1
16	16	-	-	Y12	1

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
21	1	-	D10	B15	4
21	2	174	B10	A15	4
21	3	175	E12	D14	4
21	4	-	F12	B14	4
21	5	178	-	A14	4
21	6	-	-	-	-
21	7	-	-	-	-
21	8	-	-	-	-
21	9	-	-	-	-
21	10	-	-	-	-
21	11	-	-	-	-
21	12	-	-	-	-
21	13	-	-	D13	4
21	14	-	-	C13	4
21	15	-	-	B13	4
21	16	-	-	A13	4
22	1	149	G13	F22	4
22	2	148	F15	G19	4
22	3	147	G14	G20	4
22	4	146	E16	G21	4
22	5	-	-	-	-
22	6	-	-	-	-
22	7	-	-	-	-
22	8	-	-	-	-
22	9	-	-	-	-
22	10	-	-	-	-
22	11	-	-	-	-
22	12	-	-	-	-
22	13	145	H12	G22	4
22	14	144	F16	H19	4
22	15	143	H16	H20	4
22	16	142	-	H21	4

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
23	1	179	B9	A12	4
23	2	180	-	D12	4
23	3	-	C9	B12	4
23	4	182	-	C12	4
23	5	-	C10	A11	4
23	6	-	-	-	-
23	7	-	-	-	-
23	8	-	-	-	-
23	9	-	-	-	-
23	10	-	-	-	-
23	11	-	-	-	-
23	12	-	-	-	-
23	13	-	-	B11	4
23	14	-	A9	C11	4
23	15	-	-	D11	4
23	16	-	D9	A10	4
24	1	140	G15	H22	4
24	2	139	H13	J19	4
24	3	138	G16	J20	4
24	4	137	H14	J21	4
24	5	-	-	-	-
24	6	-	-	-	-
24	7	-	-	-	-
24	8	-	-	-	-
24	9	-	-	-	-
24	10	-	-	-	-
24	11	-	-	-	-
24	12	-	-	-	-
24	13	136	H15	J22	4
24	14	135	J12	K19	4
24	15	134	K12	K20	4
24	16	-	J16	K21	4

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
25	1	110	R16	W22	3
25	2	111	N15	V20	3
25	3	112	M15	V21	3
25	4	113	M13	U19	3
25	5	-	-	-	-
25	6	-	-	-	-
25	7	-	-	-	-
25	8	-	-	-	-
25	9	-	-	-	-
25	10	-	-	-	-
25	11	-	-	-	-
25	12	-	-	-	-
25	13	114	P16	V22	3
25	14	115	N16	U20	3
25	15	116	L14	U21	3
25	16	117	M14	U22	3
26	1	109	N14	Y22	3
26	2	108	T16	W21	3
26	3	107	R15	W20	3
26	4	106	P15	Y21	3
26	5	-	P14	Y20	3
26	6	-	-	-	-
26	7	-	-	-	-
26	8	-	-	-	-
26	9	-	-	-	-
26	10	-	-	-	-
26	11	-	-	-	-
26	12	-	-	-	-
26	13	103	P13	AA22	3
26	14	102	R13	AB22	3
26	15	101	N13	AA21	3
26	16	100	R14	AB21	3

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
27	1	118	L15	T19	3
27	2	-	L13	T20	3
27	3	119	M12	T21	3
27	4	120	M16	T22	3
27	5	-	-	-	-
27	6	-	-	-	-
27	7	-	-	-	-
27	8	-	-	-	-
27	9	-	-	-	-
27	10	-	-	-	-
27	11	-	-	-	-
27	12	-	-	-	-
27	13	-	K14	R19	3
27	14	-	-	R20	3
27	15	121	-	R21	3
27	16	-	-	R22	3
28	1	99	T15	W19	3
28	2	97	R12	AA20	3
28	3	95	T14	Y18	3
28	4	-	N11	AA19	3
28	5	-	P11	W17	3
28	6	-	-	-	-
28	7	-	-	-	-
28	8	-	-	-	-
28	9	-	-	-	-
28	10	-	-	-	-
28	11	-	-	-	-
28	12	-	-	-	-
28	13	-	M11	Y17	3
28	14	-	T13	AA18	3
28	15	-	N10	AB18	3
28	16	-	-	AA17	3

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
29	1	-	L16	P19	3
29	2	-	-	P20	3
29	3	122	-	P21	3
29	4	123	-	P22	3
29	5	-	-	-	-
29	6	-	-	-	-
29	7	-	-	-	-
29	8	-	-	-	-
29	9	-	-	-	-
29	10	-	-	-	-
29	11	-	-	-	-
29	12	-	-	-	-
29	13	-	-	N19	3
29	14	125	K15	N21	3
29	15	-	L12	N22	3
29	16	-	-	M22	3
30	1	-	-	AB17	3
30	2	91	T12	W16	3
30	3	90	P10	Y16	3
30	4	89	T11	AA16	3
30	5	-	R10	AB16	3
30	6	-	-	-	-
30	7	-	-	-	-
30	8	-	-	-	-
30	9	-	-	-	-
30	10	-	-	-	-
30	11	-	-	-	-
30	12	-	-	-	-
30	13	88	M10	W15	3
30	14	87	T10	Y15	3
30	15	-	M9	AA15	3
30	16	86	R9	AB15	3

Pin Descriptions (Continued)

Function Block	Macro-cell	PQ208	FT256	FG324	I/O Bank
31	1	126	K16	M19	3
31	2	-	-	M20	3
31	3	127	-	M21	3
31	4	128	J14	L22	3
31	5	-	-	-	-
31	6	-	-	-	-
31	7	-	-	-	-
31	8	-	-	-	-
31	9	-	-	-	-
31	10	-	-	-	-
31	11	-	-	-	-
31	12	-	-	-	-
31	13	-	-	L21	3
31	14	-	J15	L20	3
31	15	-	-	L19	3
31	16	131	J13	K22	3
32	1	85	P9	W14	3
32	2	84	N9	Y14	3
32	3	-	T9	AA14	3
32	4	83	M8	AB14	3
32	5	-	T8	W13	3
32	6	-	-	-	-
32	7	-	-	-	-
32	8	-	-	-	-
32	9	-	-	-	-
32	10	-	-	-	-
32	11	-	-	-	-
32	12	-	-	-	-
32	13	82	P8	Y13	3
32	14	80	R8	AA13	3
32	15	-	T7	AB13	3
32	16	-	N8	W12	3

Notes:

1. GTS = global output enable, GSR = global reset/set, GCK = global clock, CDRST = clock divide reset, DGE = DataGATE enable.
2. GCK, GSR, and GTS pins can also be used for general purpose I/O.

XC2C512 JTAG, Power/Ground, No Connect Pins and Total User I/O

Pin Type	PQ208	FT256	FG324
TCK	98	P12	Y19
TDI	94	R11	AB19
TDO	176	A10	C14
TMS	96	N12	AB20
V _{CCAUX} (JTAG supply voltage)	11	F4	F1
Power internal (V _{CC})	1, 53, 124	P3, K13, D12, D5	E3, AA3, N20, A20, D4
Power Bank 1 I/O (V _{CCIO1})	33, 59, 79	J6, K6, L7, L8	M9, N9, P10, P11
Power Bank 2 I/O (V _{CCIO2})	26, 204	F7, F8, G6, H6	J10, J11, K9, L9
Power Bank 3 I/O (V _{CCIO3})	92, 105, 132	J11, K11, L9, L10	M14, N14, P12, P13
Power Bank 4 I/O (V _{CCIO4})	133, 157, 172, 181	F9, F10, H11	J12, J13, K14, L14
Ground	13, 24, 42, 52, 68, 81, 93, 104, 129, 130, 141, 156, 177, 190, 207	F6, F11, G7, G8, G9, G10, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10, L6, L11	D5, D18, E4, E19, J9, J14, K10, K11, K12, K13, L10, L11, L12, L13, M10, M11, M12, M13, N10, N11, N12, N13, P9, P14, V4, V19, W5, W18
No connects	-	-	-
Total user I/O (includes dual function pins)	173	212	270

Device Part Marking

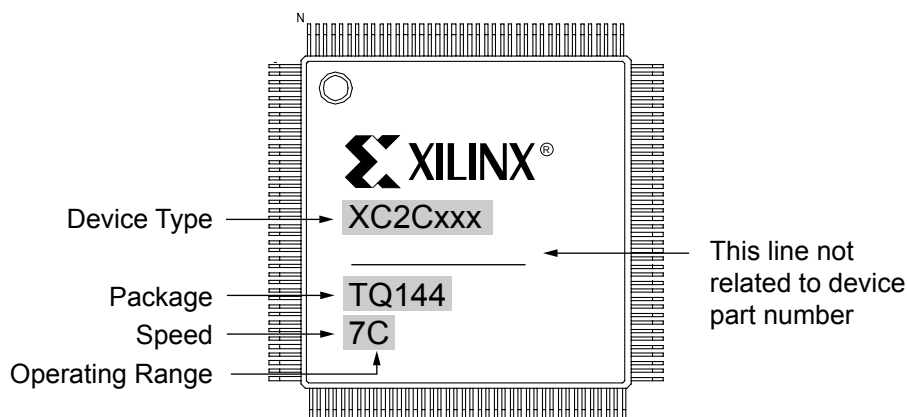


Figure 5: Sample Package with Part Marking

Ordering Information

Part Number	Pin/Ball Spacing	θ_{JA} (C/Watt)	θ_{JC} (C/Watt)	Package Type	Package Body Dimensions	I/O	Commercial (C) Industrial (I) ⁽¹⁾
XC2C512-7PQ208C	0.5mm	35.1	7.2	Plastic Quad Flat Pack	28mm x 28mm	173	C
XC2C512-10PQ208C	0.5mm	35.1	7.2	Plastic Quad Flat Pack	28mm x 28mm	173	C
XC2C512-7FT256C	1.0mm	32.2	4.9	Fine Pitch Thin BGA	17mm x 17mm	212	C
XC2C512-7FT256I	1.0mm	32.2	4.9	Fine Pitch Thin BGA	17mm x 17mm	212	I
XC2C512-10FT256C	1.0mm	32.2	4.9	Fine Pitch Thin BGA	17mm x 17mm	212	C
XC2C512-7FG324C	1.0mm	39.1	5.0	Fine Pitch BGA	23mm x 23mm	270	C
XC2C512-10FG324C	1.0mm	39.1	5.0	Fine Pitch BGA	23mm x 23mm	270	C
XC2C512-7PQG208C	0.5mm	35.1	7.2	Plastic Quad Flat Pack; Pb-free	28mm x 28mm	173	C
XC2C512-10PQG208C	0.5mm	35.1	7.2	Plastic Quad Flat Pack; Pb-free	28mm x 28mm	173	C
XC2C512-7FTG256C	1.0mm	32.2	4.9	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	212	C
XC2C512-7FTG256I	1.0mm	32.2	4.9	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	212	I
XC2C512-10FTG256C	1.0mm	32.2	4.9	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	212	C
XC2C512-7FGG324C	1.0mm	39.1	5.0	Fine Pitch BGA; Pb-free	23mm x 23mm	270	C
XC2C512-10FGG324C	1.0mm	39.1	5.0	Fine Pitch BGA; Pb-free	23mm x 23mm	270	C
XC2C512-10PQ208I	0.5mm	35.1	7.2	Plastic Quad Flat Pack	28mm x 28mm	173	I
XC2C512-10FT256I	1.0mm	32.2	4.9	Fine Pitch Thin BGA	17mm x 17mm	212	I
XC2C512-10FG324I	1.0mm	39.1	5.0	Fine Pitch BGA	23mm x 23mm	270	I
XC2C512-10PQG208I	0.5mm	35.1	7.2	Plastic Quad Flat Pack; Pb-free	28mm x 28mm	173	I
XC2C512-10FTG256I	1.0mm	32.2	4.9	Fine Pitch Thin BGA; Pb-free	17mm x 17mm	212	I
XC2C512-10FGG324I	1.0mm	39.1	5.0	Fine Pitch BGA; Pb-free	23mm x 23mm	270	I

Notes:

1. C = Commercial ($T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$); I = Industrial ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$).

Standard Example: XC2C128 -7 TQ 144 C

Device _____
 Speed Grade _____
 Package Type _____
 Number of Pins _____
 Temperature Range _____

Pb-Free Example: XC2C128 -7 TQ G 144 C

Device _____
 Speed Grade _____
 Package Type _____
 Pb-Free _____
 Number of Pins _____
 Temperature Range _____

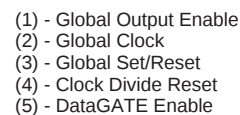


Figure 6: PQ208 Plastic Quad Flat Pack

	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
A	I/O	I/O	VCC	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O(3)	I/O
B	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O(1)
C	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	TDO	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O(1)
D	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	VCC	I/O(1)	I/O	I/O
E	I/O	I/O	I/O	GND															GND	VCC	I/O	I/O(1)
F	I/O	I/O	I/O	I/O															I/O	I/O	I/O	VAUX
G	I/O	I/O	I/O	I/O															I/O	I/O	I/O	I/O
H	I/O	I/O	I/O	I/O															I/O	I/O	I/O	I/O
J	I/O	I/O	I/O	I/O					GND	VCCIO4	VCCIO4	VCCIO2	VCCIO2	GND					I/O	I/O	I/O	I/O
K	I/O	I/O	I/O	I/O					VCCIO4	GND	GND	GND	GND	VCCIO2					I/O	I/O	I/O	I/O
L	I/O	I/O	I/O	I/O					VCCIO4	GND	GND	GND	GND	VCCIO2					I/O	I/O	I/O	I/O
M	I/O	I/O	I/O	I/O					VCCIO3	GND	GND	GND	GND	VCCIO1					I/O	I/O	I/O	I/O
N	I/O	I/O	VCC	I/O					VCCIO3	GND	GND	GND	GND	VCCIO1					I/O	I/O	I/O	I/O
P	I/O	I/O	I/O	I/O					GND	VCCIO3	VCCIO3	VCCIO1	VCCIO1	GND					I/O	I/O	I/O	I/O
R	I/O	I/O	I/O	I/O															I/O	I/O	I/O	I/O
T	I/O	I/O	I/O	I/O															I/O	I/O	I/O	I/O
U	I/O	I/O	I/O	I/O															I/O	I/O	I/O	I/O
V	I/O	I/O	I/O	GND															GND	I/O(2)	I/O	I/O
W	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O
Y	I/O	I/O	I/O	TCK	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O(2)
AA	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O(5)	I/O	VCC	I/O	I/O
AB	I/O	I/O	TMS	TDI	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O(2)	I/O(4)	I/O

FG324 Bottom View

- (1) - Global Output Enable
- (2) - Global Clock
- (3) - Global Set/Reset
- (4) - Clock Divide Reset
- (5) - DataGATE Enable

Figure 8: FG324 Fine Pitch BGA

Warranty Disclaimer

THESE PRODUCTS ARE SUBJECT TO THE TERMS OF THE XILINX LIMITED WARRANTY WHICH CAN BE VIEWED AT <http://www.xilinx.com/warranty.htm>. THIS LIMITED WARRANTY DOES NOT EXTEND TO ANY USE OF THE PRODUCTS IN AN APPLICATION OR ENVIRONMENT THAT IS NOT WITHIN THE SPECIFICATIONS STATED ON THE THEN-CURRENT XILINX DATA SHEET FOR THE PRODUCTS. PRODUCTS ARE NOT DESIGNED TO BE FAIL-SAFE AND ARE NOT WARRANTED FOR USE IN APPLICATIONS THAT POSE A RISK OF PHYSICAL HARM OR LOSS OF LIFE. USE OF PRODUCTS IN SUCH APPLICATIONS IS FULLY AT THE RISK OF CUSTOMER SUBJECT TO APPLICABLE LAWS AND REGULATIONS.

Additional Information

Additional information is available for the following CoolRunner-II topics:

- XAPP784: Bulletproof CPLD Design Practices
- XAPP375: Timing Model
- XAPP376: Logic Engine
- XAPP378: Advanced Features
- XAPP382: I/O Characteristics
- XAPP389: Powering CoolRunner-II
- XAPP399: Assigning VREF Pins

To access these and all application notes with their associated reference designs, click the following link and scroll down the page until you find the document you want:

[CoolRunner-II Data Sheets and Application Notes](#)
[Device Packages](#)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
7/19/02	1.0	Initial Xilinx release.
3/15/03	2.0	Added characterization data.
11/25/03	2.1	Fixed two typos.
1/26/04	2.2	Updated T _{sol} ; added links to Data Sheets and Application Notes.
8/03/04	2.3	Pb-free documentation
10/01/04	2.4	Add Asynchronous Preset/Reset Pulse Width specification to AC Electrical Characteristics.
01/30/05	2.5	Change to I _{CCSB} MAX for Commercial and Industrial.
03/07/05	2.6	Removed -6 speed grade. Modified Table 1, IOSTANDARDS.
03/20/06	3.0	Change to Product Specification. Add warranty Disclaimer. Add note to Pin Descriptions that GCK, GSR, and GTS pins can also be used for general purpose I/O.
02/15/07	3.1	Corrections to timing parameters t _{DIN} , t _{SUD} , t _{PSUD} , t _{PHD} , t _{PH} , t _{SLEW18} , t _{IN} (HSTL), t _{OUT} (SSTL3), and t _{Tin} (SSTL3) for -6 speed grade. Corrections to t _{DIN} , t _{SUD} , t _{CO} , t _{PSUD} , t _{PHD} , and t _{PH} for the -7 speed grade. Values now match the software. There were no changes to silicon or characterization. Added XC2C512-7FT256I and XC2C512-7FTG236I packages. Change to V _{IH} specification for 2.5V and 1.8V LVCMOS.
03/08/07	3.2	Fixed typo in note for V _{IL} for LVCMOS18; removed note for V _{IL} for LVCMOS33.